

**AMENDMENTS TO THE CLAIMS**

Claim 1 (currently amended): A package structure comprising:

- 5       a lead frame having a plurality of first leads, each of which includes a first  
          recession;  
          at least a ~~first device~~ semiconductor chip; and  
          a plurality of first solder joints respectively positioned in the first recessions for  
          connecting the ~~first device~~ semiconductor chip to the lead frame.

- 10    Claim 2 (currently amended) The package structure of claim 1 wherein the ~~first device is~~  
          ~~a semiconductor chip~~. lead frame further comprises a plurality of second leads, each of  
          which includes a second recession.

- 15    Claim 3 (currently amended): The package structure of claim ~~1~~2 wherein the ~~first device~~  
          ~~is a passive device~~. package structure comprises at least one passive device having a  
          plurality of outputs respectively positioned in the second recessions, and a plurality of  
          second solder joints respectively positioned in the second recessions for connecting the  
          passive device to the lead frame.

- 20    Claim 4 (original): The package structure of claim 3 wherein the passive device is an  
          electrical resistor, a capacitor, or an inductor.

Claim 5 (cancelled)

- 25    Claim 6 (cancelled)

Claim 7 (cancelled)

Claim 8 (cancelled)

Claim 9 (currently amended): The package structure of claim 8~~3~~ wherein the ~~second device is a semiconductor die and the second solder joints~~ is are composed comprised of tin or tin alloy.

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Claim 10 (currently amended): The package structure of claim 2~~1~~ wherein the lead frame comprises a die pad connected to the ~~first device semiconductor chip~~ for radiating the heat produced by the ~~first device semiconductor chip~~ by serving as a heat sink.

10 Claim 11 (currently amended): The package structure of claim 10 wherein the ~~chip sink die pad includes comprises~~ a ground pad connected to both ground and the ~~first device semiconductor chip~~.

15 Claim 12 (currently amended): The package structure of claim 1 wherein the first solder joints is are composed comprised of tin or tin alloy.

Claim 13 (new): The package structure comprising:

a lead frame having a plurality of first leads, wherein at least two of the first leads comprises a first recession;

20 at least a passive device, wherein each output of the passive device is respectively positioned in the first recession; and

a plurality of first solder joints respectively positioned in the first recessions for connecting the passive device to the lead frame.

25 Claim 14 (new): The package structure of claim 13 wherein the package structure further comprises a semiconductor chip and a plurality of leading wires, wherein the semiconductor chip is connected to the leading wires.

Claim 15 (new): The package structure of claim 13 wherein the passive device is an electrical resistor, a capacitor, or an inductor.

Claim 16 (new): The package structure of claim 13 wherein the first solder joints are comprised of tin or tin alloy.

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